

Preliminary

Messrs.

Shock Sensor Specification

Part No. : PSCE242K-R090C

RoHS Compliant

Halogen-Free Compliant

16. Dec. 2010

Approved by Kazuki Shimizu

Checked by Yasuhiro Nakai

Issued by Akira Oikawa

KYOCERA CORPORATION

Modification Table

No.	Date	Change	Apploved	Checked	Issued
00	16 th .Dec 2010	The first edition	Kazuki Shimizu	Yasuhiro Nakai	Akira Oikawa

Preliminary**1.Scope**

This specification shall cover the characteristics of the shock sensor.

2.Kyocera's Type Name**PSCE242K-R090C****3.Customer's Type Name****4.Electrical Characteristics**

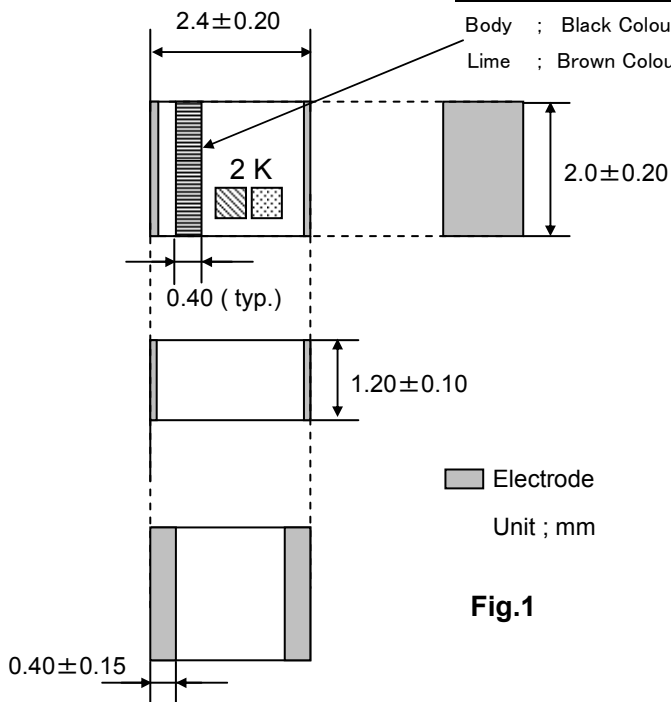
Items	Specifications
4-1 Primary Axis Inclined Angle	$25 \pm 3^\circ$
4-2 Capacitance	$315\text{pF} \pm 30\%$, at 1Vrms, 1kHz
4-3 Charge Sensitivity	$0.055\text{pC/G} \pm 40\%$, under vibration at 200Hz, 2G
4-4 Insulation Resistance	0.5Gohm minimum, at 10VDC(charging time 200msec)
4-5 Resonant Frequency	90.0 kHz $\pm 20\%$
4-6 Non-linearity	5% maximum, under vibration at 25G
(Reference only) Voltage Sensitivity	0.175 mV/G, under vibration at 200Hz, 2G

<Measurement Condition>

The reference temperature shall be $25^\circ\text{C} \pm 5^\circ\text{C}$.

5.Dimensions and Marking**Marking of Polarity**

Body ; Black Colour
Lime ; Brown Colour

**Fig.1****Characteristic Spec**

2 ; Initial Primary Axis Inclined Angle

K ; Electrical Characteristics

Manufacturing Day Code :

Day	1	2	3	4	5	6	7	8	9	10	
Cade	A	B	C	D	E	F	G	H	J	K	
Day	11	12	13	14	15	16	17	18	19	20	
Cade	L	M	N	P	Q	R	S	T	U	V	
Day	21	22	23	24	25	26	27	28	29	30	31
Cade	W	X	Y	Z	a	b	c	d	e	f	g

EIAJ Date Code :

2009 Jan. ~ Dec. : A ~ M except "I"

2010 Jan. ~ Dec. : N ~ Z except "O"

2011 Jan. ~ Dec. : a ~ m except "i"

2012 Jan. ~ Dec. : n ~ z except "o"

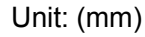
Note : These alphabets should be repeated after Jan. 2013

6.Environmental Characteristics**Preliminary**

Items	Conditions
6-1.High Temperature Storage Test	Keep in a chamber at $85 \pm 2^{\circ}\text{C}$ for $1000 +12/-0$ hours, and then keep at room temperature for 1 hour. The characteristics of shock sensor shall meet the specifications.
6-2.Low Temperature Storage Test	Keep in a chamber at $-40 \pm 2^{\circ}\text{C}$ for $1000 +12/-0$ hours, and then keep at room temperature for 1 hour. The characteristics of shock sensor shall meet the specifications.
6-3.Moisture Resistance Test	Keep in a chamber at 90 to 95 % R.H. and $60 \pm 2^{\circ}\text{C}$ for $500 +12/-0$ hours, and then keep at room temperature for 1 hour. The characteristics of shock sensor shall meet the specifications.
6-4.Temperature Cycling Test	Apply 100 thermal cycles with the following temperatures: - upper temperature 85°C for 20 minutes and transfer time 10 minutes - lower temperature -40°C for 20 minutes and transfer time 10 minutes - total cycle time is 1hour and then left at room temperature for 1 hour. The characteristics of shock sensor shall meet the specifications.
6-5.Mechanical Shock Test	After applying the acceleration at 29430m/sec^2 {3000G} in each of X, Y and Z axis (each 3 times). The characteristics of shock sensor shall meet the specifications.
6-6.Solderability Test	At first, being soaked in the Methanol solution containing Rosin for 5 seconds and then being dipped in a bath of Pb/Sn solder at $250 \pm 5^{\circ}\text{C}$ for 4 ± 0.5 seconds. The surface of the electrode terminal shall be soldered more than 95%.
6-7.Resistance to Soldering Heat Test	Pre-heat temperature is 150 to 180°C for 1 minute. High temperature is $250 \pm 5^{\circ}\text{C}$, over 200°C for 20 seconds max.(2times). Then keep at room temperature for 1 hour. The characteristics of shock sensor shall meet the specifications.
6-8.Board Flex Test	After soldered on the circuit board specified as below, then the load which cause 3 mm bend to the board is applied. The characteristics of shock sensor shall meet the specifications. The shock sensor cause no defect in the appearance. (Circuit Board: FR4, 100 x 40 x 1.6)

<Measurement Condition>The reference temperature shall be $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$.

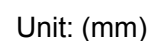
Preliminary



8. Recommended Convection Reflow profile



9-1-1.Dimensions



Sym bol	Dimensions	Sym bol	Dimensions
A_0	2.3 ± 0.1	P_0	4.0 ± 0.1
B_0	2.7 ± 0.1	P_1	4.0 ± 0.1
W	12.0 ± 0.2	D_0	$1.5 + 0.1/-0$
E	1.75 ± 0.1	K	1.5 ± 0.1
F	5.5 ± 0.1	T	0.3 ± 0.1

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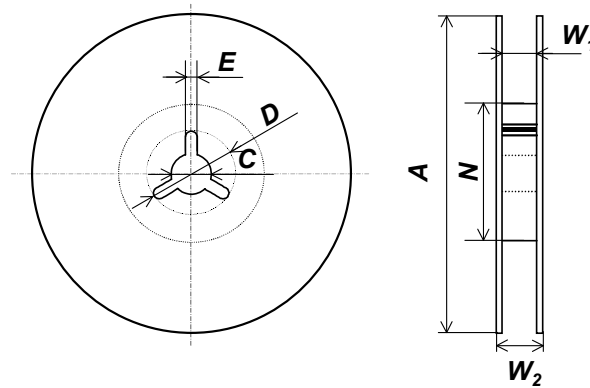
9-2. Taping

Preliminary

9-2-1. Taping Quantity

One reel of the carrier tape shall pack 3000 pcs. Shock sensor shall be contained in pocket continuously.

9-2-2. Dimensions

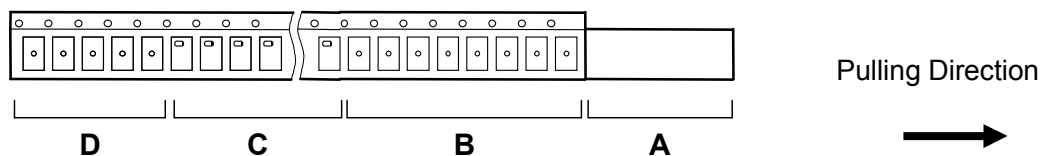
**Fig.5 Reel**

Unit: (mm)

Symbol	A	N	W₁	W₂
Dimensions	180±5.0	60min.	12.5 +2.0/-0.0	20.5 max.
Symbol	C	D	E	
Dimensions	13.0±0.2	21.0±0.8	2.0±0.5	

9-2-3. Leader and Blank Pocket

Package shall consist of leader, blank pocket and loaded pocket as follows. (fig.6)



A) Leader

B) Blank Pocket (160mm Min.)

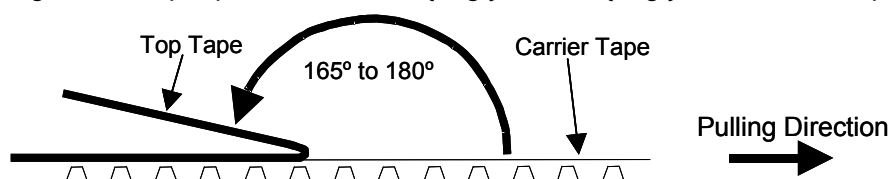
A+B: 400mm to 560mm

C) Load Pocket

D) Blank Pocket (40 to 190mm)

Fig.6 Packing Method

Peeling load of top tape shall be 0.1N {10gf} to 0.7N {70gf} from Carrier Tape.

**Fig.7 Peeling Strength**

Preliminary**9-2-4. Reel label**

A reel label shall be contained as below: (Based on EIAJ C-3 format)

- A) Customer P/N
- B) Lot No.
- C) Quantity
- D) Shipping date
- E) Vender Name

9-2-5. Exterior Package label

Shock sensor shall be packed properly to avoid defect in transportation and the marking of exterior package shall be contained as below:

- A) Name of Customer
- B) P/O No.
- C) Customer P/N
- D) Lot No.
- E) Quantity
- F) Shipping Date

10. The agreement of this specifications

Should any part of the content of this specification become questionable, it shall be settled by mutual deliberations.

11. Caution for handling

- A) Shock and or vibration to piece parts shall not be exceed the defined specification.
- B) This parts cannot washing and cleaning after soldering process.
- C) Maximum temperature is 280 degree.
- D) Notes in soldering

Solder iron temp: 350 ± 10 degrees C

Heat time:Max 3 seconds (Accumulated time)

- Please take care of solder iron not to attach products directly.
- Please use new product attached no solder when you rework.

12.RoHS Compliant

- A) Sensor Case: Epoxy resin
- B) Terminal: Ag paste (thickness 30 um)
Plating: Ni(2um), Sn(5 um)
- C) Element: Piezo Ceramic, contains lead-oxide, however, piezo-electronic devices are exempted from RoHS compliant requirement of article 4(1).
(Refer to Annex, Section 7)

All materials meet to RoHS Compliant.

13. Halogen-Free Compliant**Preliminary**

- A) Bromine(Br) <900ppm(0.09%)
- B) Chlorine(Cl) <900ppm(0.09%)
- C) Total concentration of Chlorine(Cl)+Bromine(Br) <1500ppm(0.15%)
- D) Antimony Trioxide(Sb_2O_3) <1000ppm(0.1%)
- E) Red Phosphorus <1000ppm(0.1%)

All materials meet to Halogen-Free Compliant.

14. Others

There is a possibility of changing the specification by the result of review in the future.